DATA BOOK
PACKAGE OUTLINE

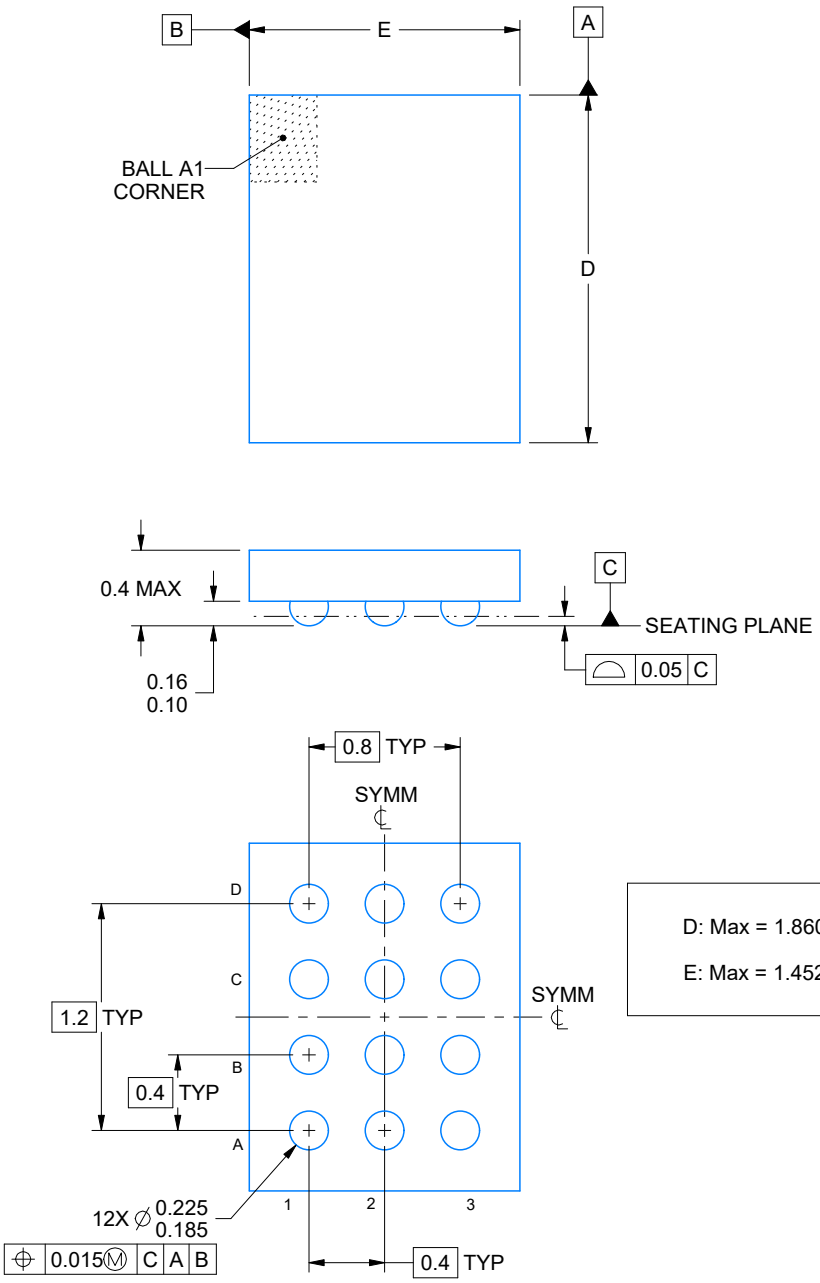
DRAFTER: K. SINCERBOX	DATE: 01/14/2022		DIMENSIONS IN MILLIMETERS
DESIGNER:	DATE:	TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295
CHECKER: K. SINCERBOX	DATE: 07/25/2022		
ENGINEER: M. XU	DATE: 07/25/2022	ePOD, YBH0012-C01 / DSBGA, 12 BALL, 0.4 MM PITCH	
APPROVED: D. CHIN & J. MARIANO	DATE: 07/25/2022		
RELEASED: K. SINCERBOX	DATE: 07/25/2022		
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	SCALE NTS / SIZE A / 4228369 / REV B / PAGE 1 OF 5	

YBH0012-C01

PACKAGE OUTLINE

DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



D: Max = 1.860 mm, Min = 1.820 mm

E: Max = 1.452 mm, Min = 1.412 mm

4228369/B 07/2022

NOTES:

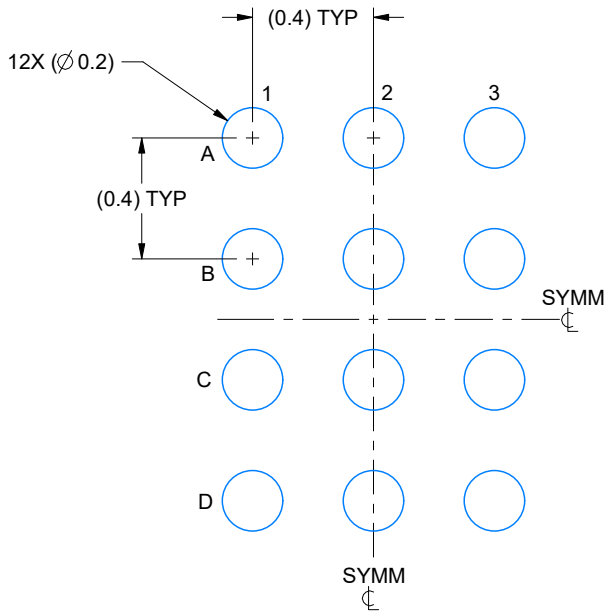
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

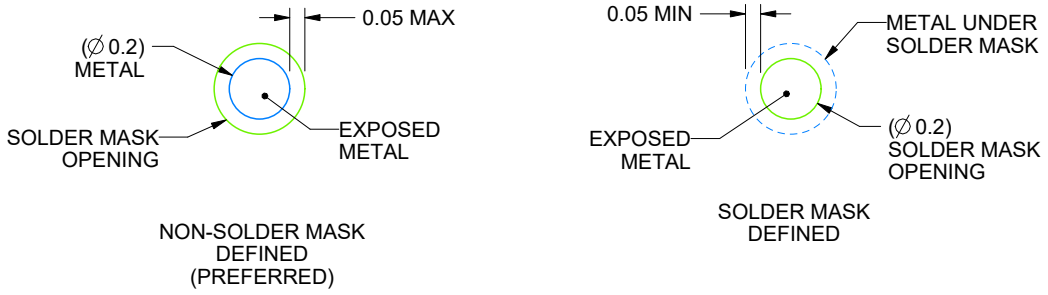
YBH0012-C01

DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 40X

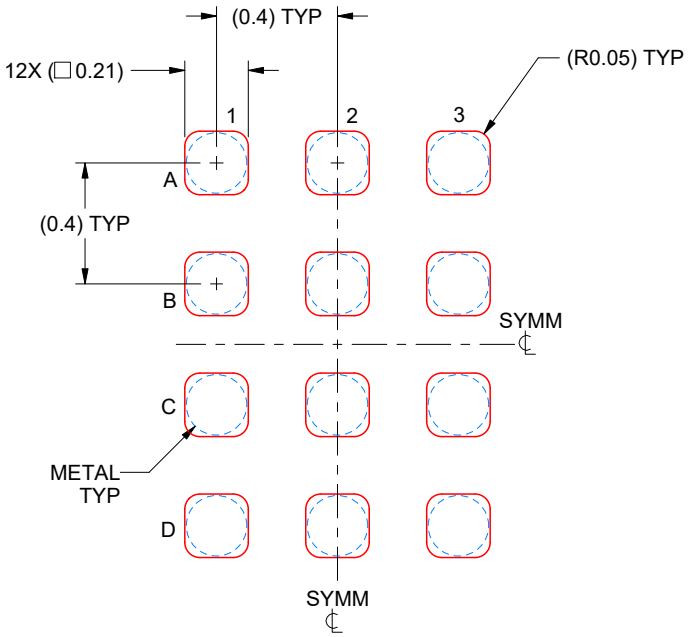


SOLDER MASK DETAILS
NOT TO SCALE

4228369/B 07/2022

NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
 See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
BASED ON 0.075 mm THICK STENCIL
SCALE: 40X

4228369/B 07/2022

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2198127	01/14/2022	M. XU / K. SINCERBOX
B	E: Max = 1.452 mm, Min = 1.412 mm WAS E: Max = 1.4 mm, Min = 1.36 mm;	2200712	07/25/2022	M. XU / K. SINCERBOX